

Fee only

Customer No.: 31561
Application No.: 10/604,743
Docket NO.: 8376-US-PA-0C

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Tong et al.
Application No. : 10/604,743
Filed : August 14, 2003
Title : SOLDER BALL FABRICATING PROCESS
Examiner : CHAMBLISS, ALONZO
Docket No. : 8376-US-PA-0C

**TERMINAL DISCLAIMER TO OBVIATE A
DOUBLE PATENTING REJECTION**

The owner, Advanced Semiconductor Engineering, Inc., of 100% percent interest in the instant application hereby disclaims, except as provided below, the terminal part of the statutory term of any patent granted on the instant application which would extend beyond the expiration date of the full statutory term defined in 35 U.S.C. 154 to 156 and 173, as presently shortened by any terminal disclaimer, of prior Patent No. 6,673,711 B2, issued Jan. 06, 2004. The owner hereby agrees that any patent so granted on the instant application shall be enforced only for and during such period that it and the prior patent are commonly owned. This agreement runs with any patent granted on the instant application and is binding upon the grantee, its successors or assigns.

In making the above disclaimer, the owner does not disclaim the terminal part of any patent granted on the instant application that would extend to the expiration date of the full statutory term as defined in 35 U.S.C. 154 TO 156 and 173 of the prior patent, as presently shortened by any terminal disclaimer, in the event that it later: expires for failure to pay a maintenance fee, is held unenforceable, is found invalid by a court of competent jurisdiction, is reissued, or is in any manner terminated prior to the expiration of its full statutory term as presently shortened by any terminal disclaimer.

1. [] For submissions on behalf of an organization (e.g., corporation, partnership, university, government agency, etc.), the undersigned is empowered to act on behalf of the organization.

I hereby declare that all statement made herein of my own knowledge are true